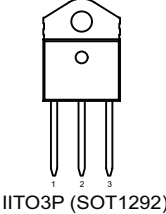
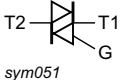


Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2+ G+ $T_J = 25\text{ }^\circ\text{C}$; Fig. 7	-	-	50	mA
		$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2+ G- $T_J = 25\text{ }^\circ\text{C}$; Fig. 7	-	-	50	mA
		$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2- G- $T_J = 25\text{ }^\circ\text{C}$; Fig. 7	-	-	50	mA
		$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2- G+ $T_J = 25\text{ }^\circ\text{C}$; Fig. 7	-	-	70	mA
I_H	holding current	$V_D = 12\text{ V}$; $T_J = 25\text{ }^\circ\text{C}$; Fig. 9	-	-	80	mA
V_T	on-state voltage	$I_T = 56.6\text{ A}$; $T_J = 25\text{ }^\circ\text{C}$; Fig. 10	-	1.2	1.5	V
Dynamic characteristics						
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 536\text{ V}$; $T_J = 125\text{ }^\circ\text{C}$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; gate open circuit	750	-	-	V/ μs
		$V_{DM} = 536\text{ V}$; $T_J = 150\text{ }^\circ\text{C}$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; gate open circuit	500	-	-	V/ μs
dI_{com}/dt	rate of change of commutating current	$V_D = 400\text{ V}$; $T_J = 125\text{ }^\circ\text{C}$; $I_{T(RMS)} = 20\text{ A}$; $dV_{com}/dt = 20\text{ V}/\mu\text{s}$; gate open circuit	20	-	-	A/ms
		$V_D = 400\text{ V}$; $T_J = 150\text{ }^\circ\text{C}$; $I_{T(RMS)} = 20\text{ A}$; $dV_{com}/dt = 20\text{ V}/\mu\text{s}$; gate open circuit	10	-	-	A/ms

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1	 ITO3P (SOT1292)	 sym051
2	T2	main terminal 2		
3	G	gate		
mb	n.c.	mounting base; isolated		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BTA41-800B	IITO3P	BTA41-800BQ	Tube	30	SOT1292	21-Jul-2017

7. Marking

Table 4. Marking codes

Type number	Marking codes
BTA41-800B	BTA41-800B

8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{DRM}	repetitive peak off-state voltage		800	V
$I_{\text{T(RMS)}}$	RMS on-state current	full sine wave; $T_{\text{mb}} \leq 105^{\circ}\text{C}$; Fig. 1 ; Fig. 2 ; Fig. 3	40	A
I_{TSM}	non-repetitive peak on-state current	full sine wave; $t_p = 20 \text{ ms}$; $T_{\text{j(init)}} = 25^{\circ}\text{C}$; Fig. 4 ; Fig. 5	400	A
		full sine wave; $t_p = 16.7 \text{ ms}$; $T_{\text{j(init)}} = 25^{\circ}\text{C}$	440	A
I^2t	I^2t for fusing	$t_p = 10 \text{ ms}$; sine wave	800	A^2s
dI_{T}/dt	rate of rise of on-state current	$I_{\text{G}} = 150 \text{ mA}$	150	$\text{A}/\mu\text{s}$
I_{GM}	peak gate current	$t_p = 20 \mu\text{s}$	8	A
P_{GM}	peak gate power	$t_p = 20 \mu\text{s}$	40	W
$P_{\text{G(AV)}}$	average gate power	over any 20 ms period	1	W
T_{stg}	storage temperature		-40 to 150	$^{\circ}\text{C}$
T_{j}	junction temperature		150	$^{\circ}\text{C}$

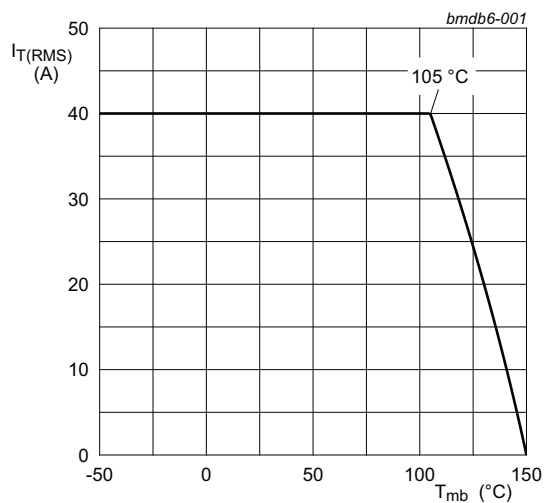
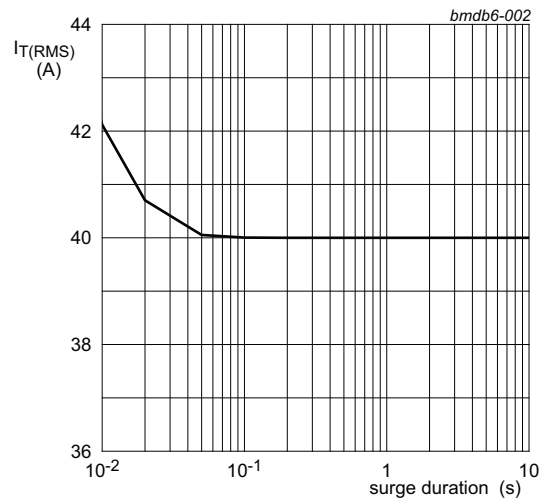


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values



$f = 50 \text{ Hz}$; $T_{\text{mb}} = 105^{\circ}\text{C}$

Fig. 2. RMS on-state current as a function of surge duration; maximum values

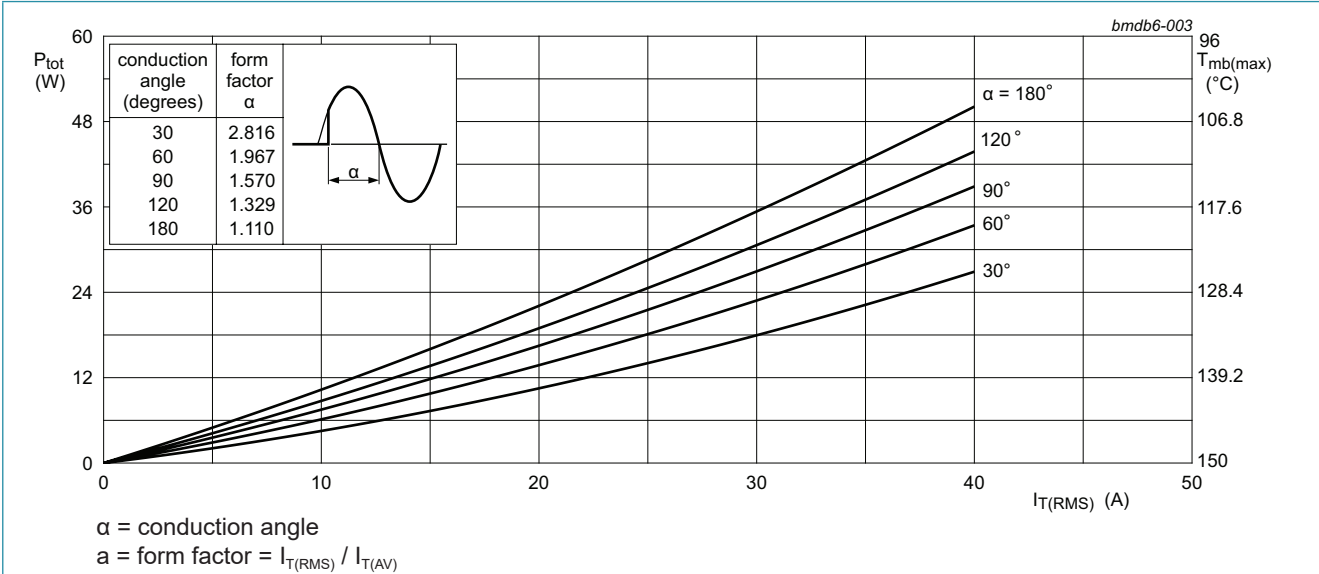


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

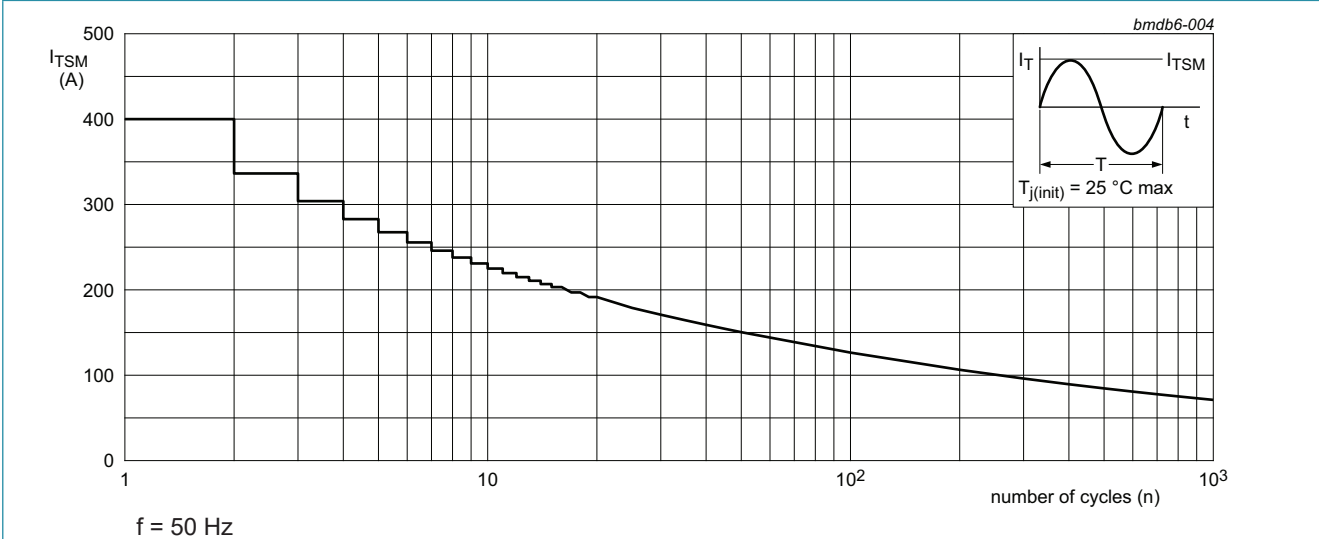


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

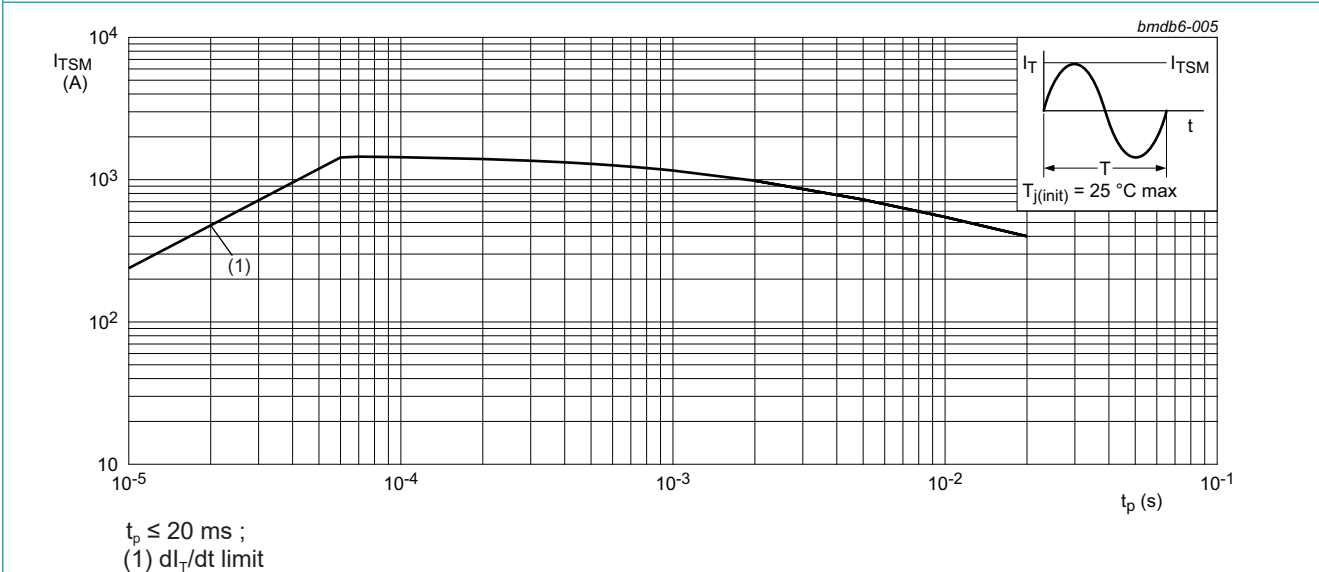
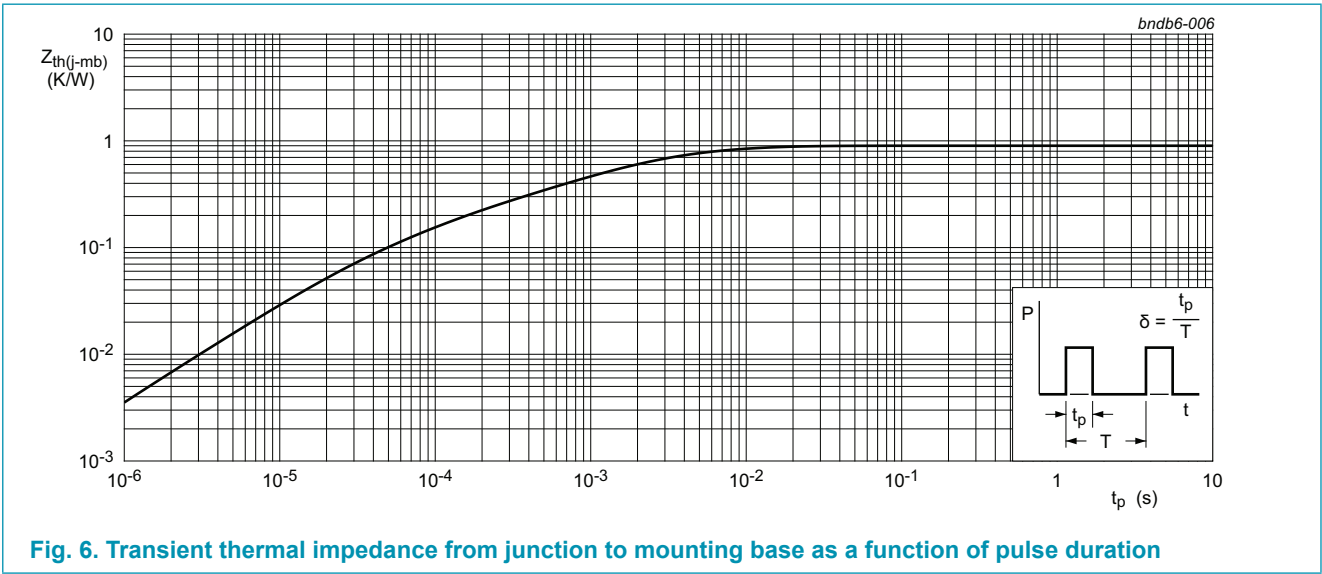


Fig. 5. Total power dissipation as a function of RMS on-state current; maximum values

9. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 6		-	-	0.9	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	50	-	K/W



10. Isolation characteristics

Table 6. Isolation characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$V_{isol(RMS)}$	RMS isolation voltage	from all terminal to external heatsink; sinusoidal waveform; clean and dust free; $50\text{ Hz} \leq f \leq 60\text{ Hz}$; $RH \leq 65\%$; $T_h = 25\text{ }^\circ\text{C}$		-	-	2500	V

11. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I _{GT}	gate trigger current	V _D = 12 V; I _T = 0.1 A; T2+ G+; T _J = 25 °C; Fig. 7		-	-	50	mA
		V _D = 12 V; I _T = 0.1 A; T2+ G-; T _J = 25 °C; Fig. 7		-	-	50	mA
		V _D = 12 V; I _T = 0.1 A; T2- G-; T _J = 25 °C; Fig. 7		-	-	50	mA
		V _D = 12 V; I _T = 0.1 A; T2- G+; T _J = 25 °C; Fig. 7		-	-	70	mA
I _L	latching current	V _D = 12 V; I _T = 0.1 A; T2+ G+; T _J = 25 °C; Fig. 8		-	-	100	mA
		V _D = 12 V; I _T = 0.1 A; T2+ G-; T _J = 25 °C; Fig. 8		-	-	160	mA
		V _D = 12 V; I _T = 0.1 A; T2- G-; T _J = 25 °C; Fig. 8		-	-	100	mA
		V _D = 12 V; I _T = 0.1 A; T2- G+; T _J = 25 °C; Fig. 8		-	-	100	mA
I _H	holding current	V _D = 12 V; T _J = 25 °C; Fig. 9		-	-	80	mA
V _T	on-state voltage	I _T = 56.6 A; T _J = 25 °C; Fig. 10		-	1.2	1.5	V
V _{GT}	gate trigger voltage	V _D = 12 V; I _T = 0.1 A; T _J = 25 °C; Fig. 11		-	0.8	1.3	V
		V _D = 400 V; I _T = 0.1 A; T _J = 150 °C; Fig. 11		0.2	0.45	-	V
I _D	off-state current	V _D = 800 V; T _J = 25 °C		-	-	10	μA
		V _D = 800 V; T _J = 150 °C		-	-	2.5	mA
Dynamic characteristics							
dV _D /dt	rate of rise of off-state voltage	V _{DM} = 536 V; T _J = 125 °C; (V _{DM} = 67% of V _{DRM}); exponential waveform; gate open circuit		750	-	-	V/μs
		V _{DM} = 536 V; T _J = 150 °C; (V _{DM} = 67% of V _{DRM}); exponential waveform; gate open circuit		500	-	-	V/μs
dI _{com} /dt	rate of change of commutating current	V _D = 400 V; T _J = 125 °C; I _{T(RMS)} = 20A; dV _{com} /dt = 20 V/μs; gate open circuit		20	-	-	A/ms
		V _D = 400 V; T _J = 150 °C; I _{T(RMS)} = 20A; dV _{com} /dt = 20 V/μs; gate open circuit		10	-	-	A/ms

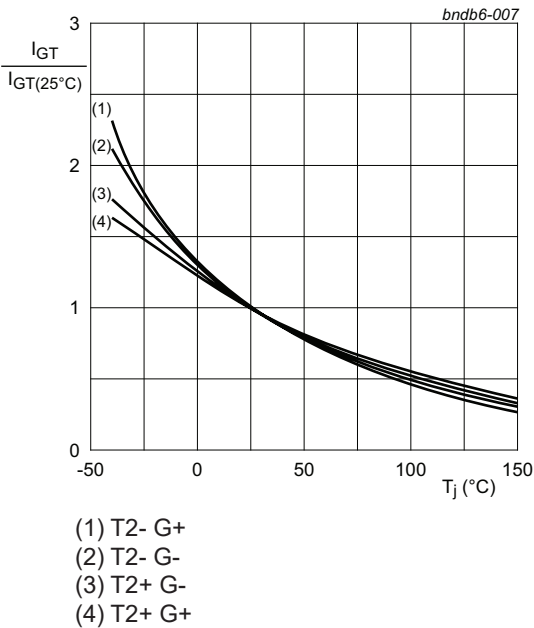


Fig. 7. Normalized gate trigger current as a function of junction temperature

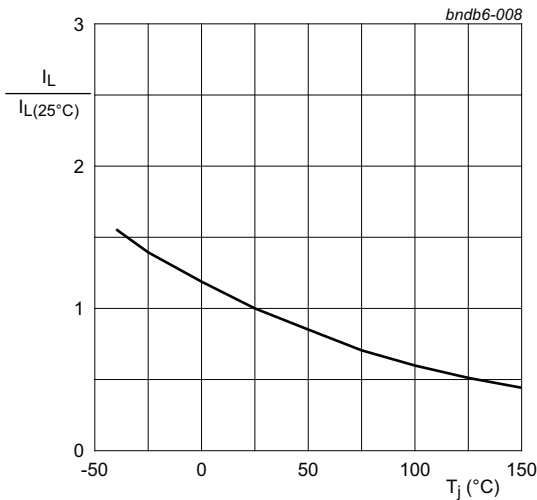


Fig. 8. Normalized latching current as a function of junction temperature

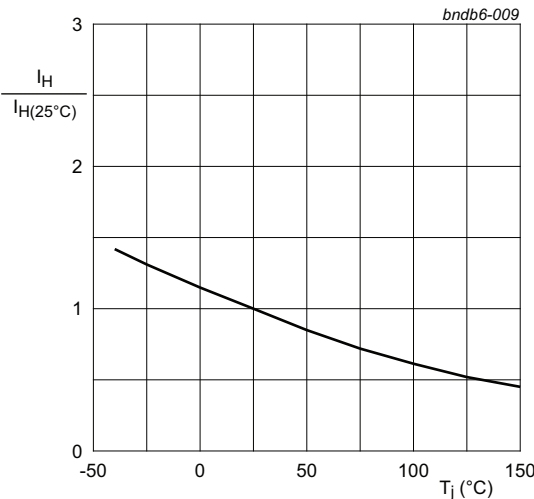
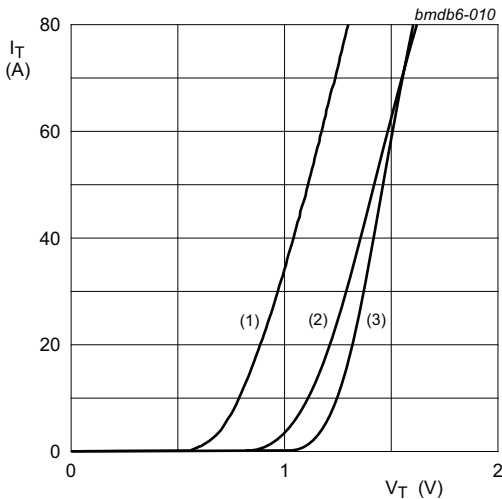


Fig. 9. Normalized holding current as a function of junction temperature



$V_o = 1.063 \text{ V}; R_s = 0.0074 \text{ } \Omega$
(1) $T_j = 150^{\circ}\text{C}$; typical values
(2) $T_j = 150^{\circ}\text{C}$; maximum values
(3) $T_j = 25^{\circ}\text{C}$; maximum values

Fig. 10. On-state current as a function of on-state voltage

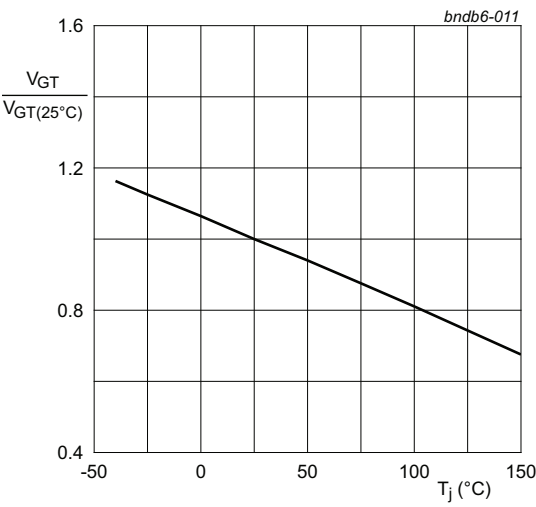


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

12. Package outline

Plastic single-ended through-hole package; isolated heatsink mounted; 1 mounting hole; 3 -lead TO3P

SOT1292

The technical drawing shows the package outline for the BTA41-800B. The top view (left) shows a rectangular body with a circular mounting hole of diameter ØL. Dimensions include H (total width), R (radius of the mounting hole), K (width of the mounting tab), L (height of the body), and J (pitch of the leads). The side view (right) shows the profile of the package with dimensions A (total height), B (height of the mounting tab), E (height of the body), D (height of the leads), and a 0.6mm dimension at the base of the leads.

Unit		A	B	C	D	E	F	G	H	J	K	L	P	R
mm	min	4.75	1.45	14.35	0.50	2.70	15.80	20.40	15.10	5.40	3.40	4.08	1.20	4.6 (typ.)
	max	4.95	1.55	15.60	0.70	2.90	16.50	21.10	15.50	5.65	3.65	4.17	1.40	

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT1292		-				

13. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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